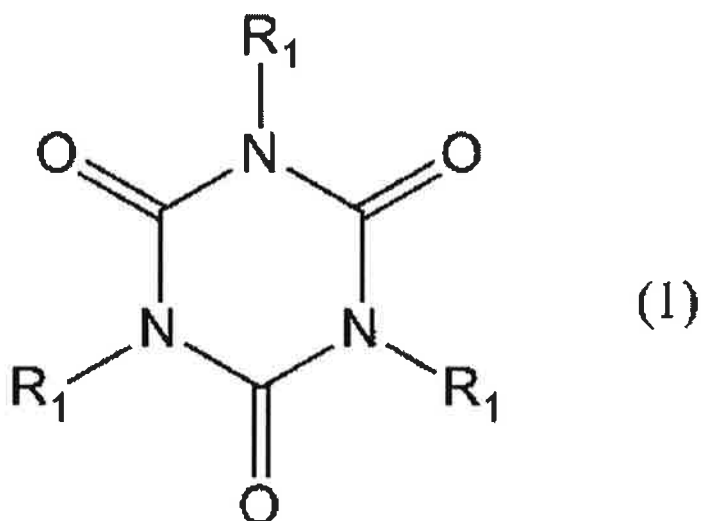


ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION AND CURED PRODUCT THEREFROM

The present invention is a negative-acting photosensitive resin composition including (A) a compound having a triazine ring and represented by formula (1) (in formula (1), each R_1 independently represents an organic group, wherein at least one R_1 represents an organic group having a glycidyl group or an organic group having an oxetanyl group), (B) an epoxy resin having in each molecule a benzene backbone and at least two epoxy groups and having an epoxy equivalent weight of not more than 500 g/eq., and (C) a cationic photopolymerization initiator. The content of the (A) compound represented by formula (1) with reference to the (B) epoxy resin is 1 to 50 mass%. The (B) epoxy resin satisfies at least one of the following conditions (i) and (ii): condition (i) a weight-average molecular weight of at least 500, and condition (ii) a softening point of at least 40°C.



[No figure]